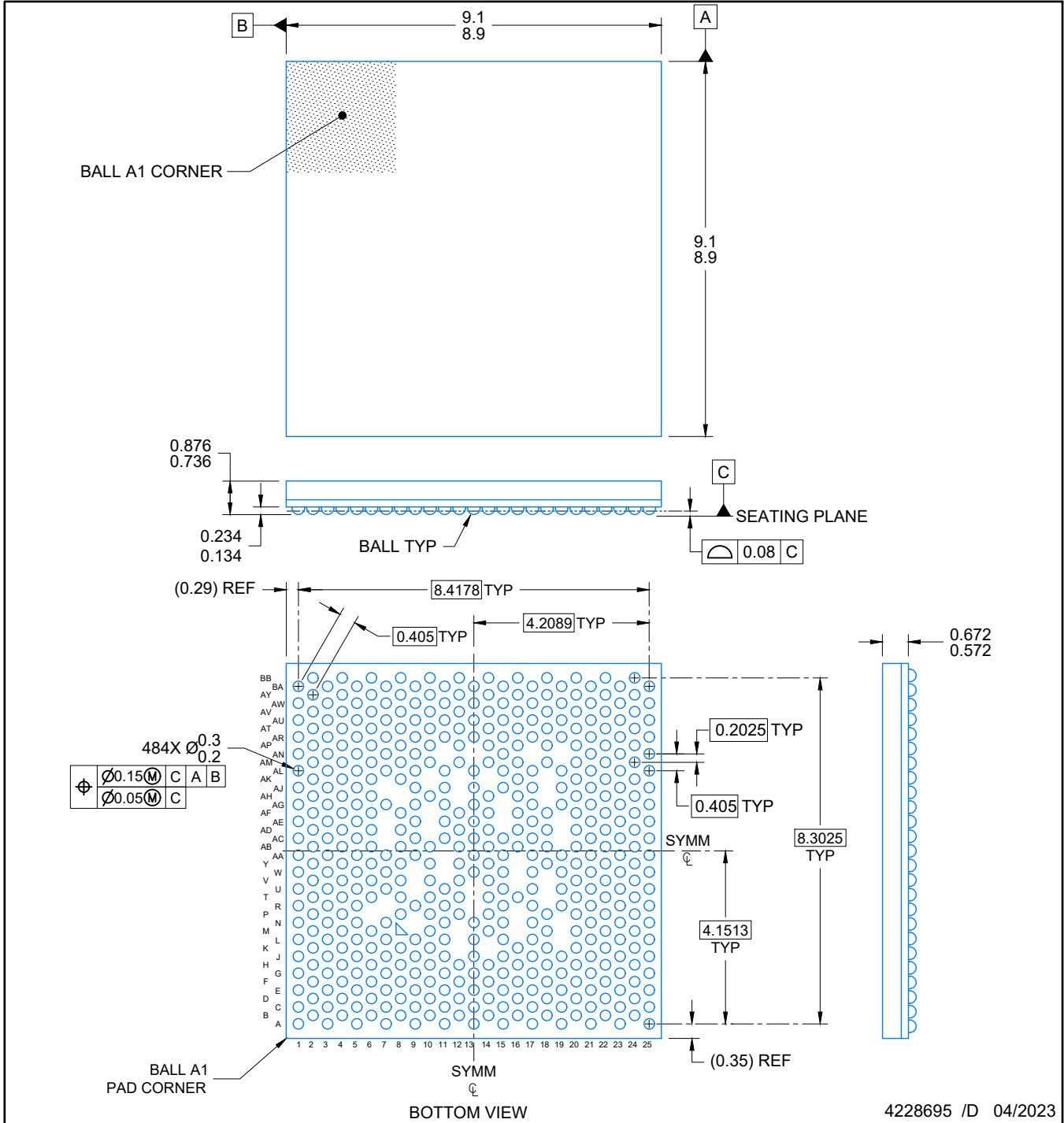


AMD0484A

PACKAGE OUTLINE FCCSP - 0.876 mm max height

Flip Chip-Chip Scale Package



NOTES:

NanoFree is a trademark of Texas Instruments.

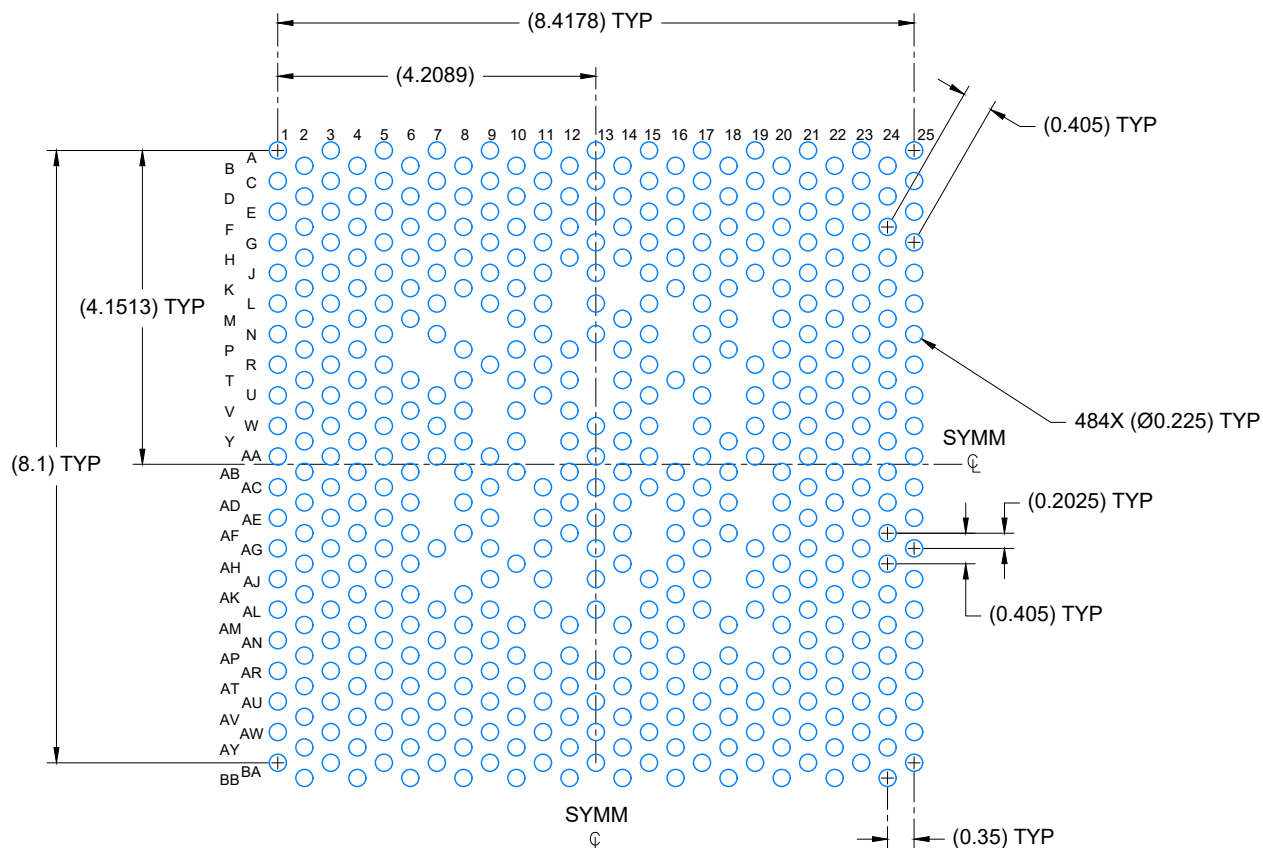
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

EXAMPLE BOARD LAYOUT

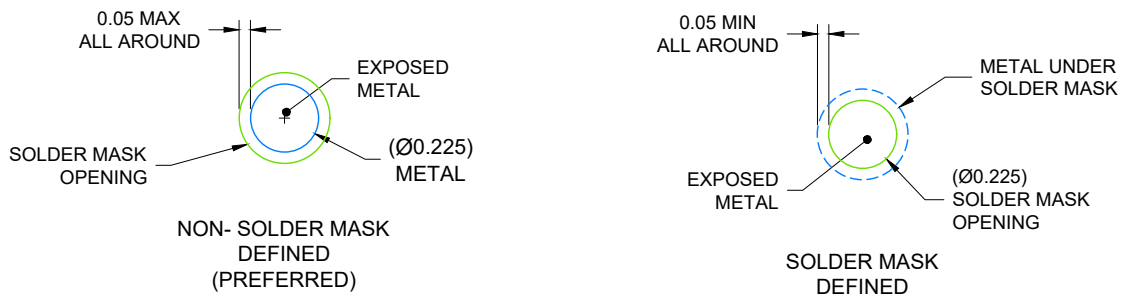
AMD0484A

FCCSP - 0.876 mm max height

Flip Chip-Chip Scale Package



LAND PATTERN EXAMPLE
SCALE: 10X



SOLDER MASK DETAILS
NOT TO SCALE

4228695 /D 04/2023

NOTES: (continued)

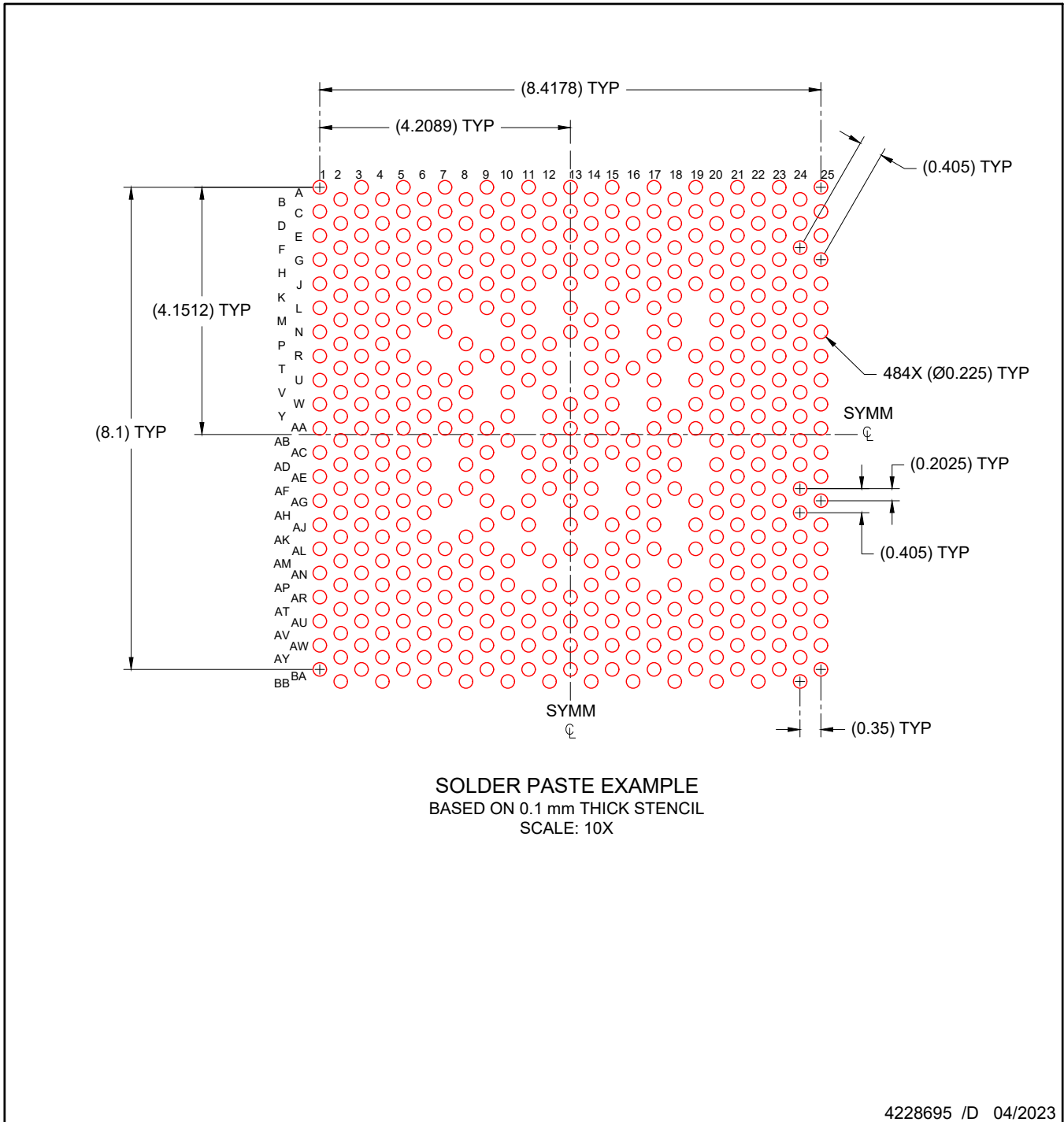
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. Refer to Texas Instruments Literature number SNVA009 (www.ti.com/lit/snva009).

EXAMPLE STENCIL DESIGN

AMD0484A

FCCSP - 0.876 mm max height

Flip Chip-Chip Scale Package



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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